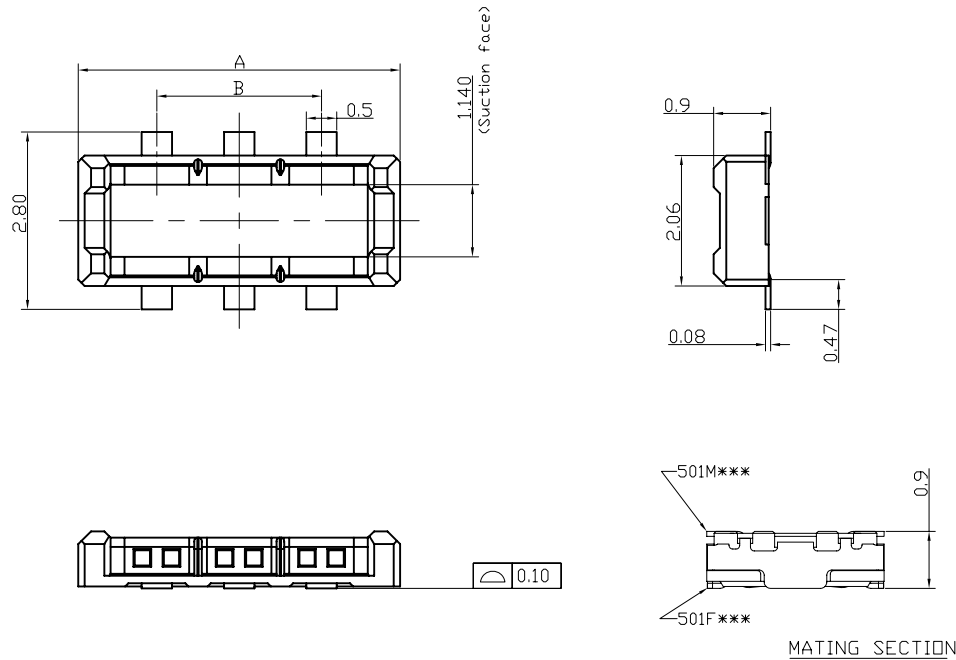


1	2	3	4	5	6	7		8		
						REV	ECN NO	DRA	APPD	DATE
						A	FIRST RELEASE	George Gao	Human Zhou	2013.11.15



Specifications:

1) Material:

1-1.Molded portion: LCP resin ( UL94 V-0)

1-2.Contact and Post: Copper alloy.

2) Surface treatment:

2-1.Terminal portion: Base: Ni plating Surface: Au plating (except the terminal tips) ; Exposed nickel portions.

2-2.Metal clips: Base: Ni plating Surface: Au flash plating (except the terminal tips) Or Base: Ni plating Surface: Sn flash plating (except the terminal tips)

3) Characteristics:

3-1. Rated voltage: 30V AC/DC

3-2. Rated current: 4.0A/contact

3-3. Insulation resistance: Min. 1000M $\Omega$  (initial)

3-4. Breakdown voltage: 500V AC for 1 min.

3-5.Saltwater spray resistance (header and socket mated): 24 hours, insulation resistance min.100M $\Omega$ , contact resistance max. 20m $\Omega$

3-6. Contact resistance: Power pin:20m $\Omega$ 、 Signal pin :50m $\Omega$

3-7. Ambient temperature: -25 $^{\circ}$ C-+85 $^{\circ}$ C

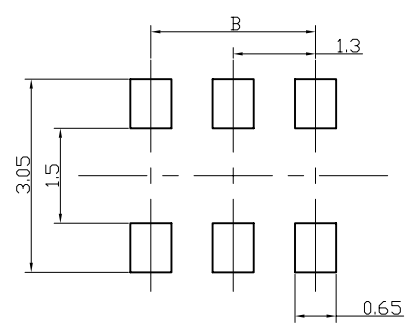
3-8. Storage temperature: -25 $^{\circ}$ C-+85 $^{\circ}$ C (product only); -40 $^{\circ}$ C-+50 $^{\circ}$ C (emboss packing)

3-9. Composite insertion force: Max. 0.981N/contacts X contacts (initial)

3-10. Composite removal force: Min. 0.165N/contacts X contacts

3-11. Post holding force: Min. 0.49N/contacts

3-12. Insertion and removal life: 30 times



OK-501M\*\*\*-13

HEADER

PITCH=1.3MM

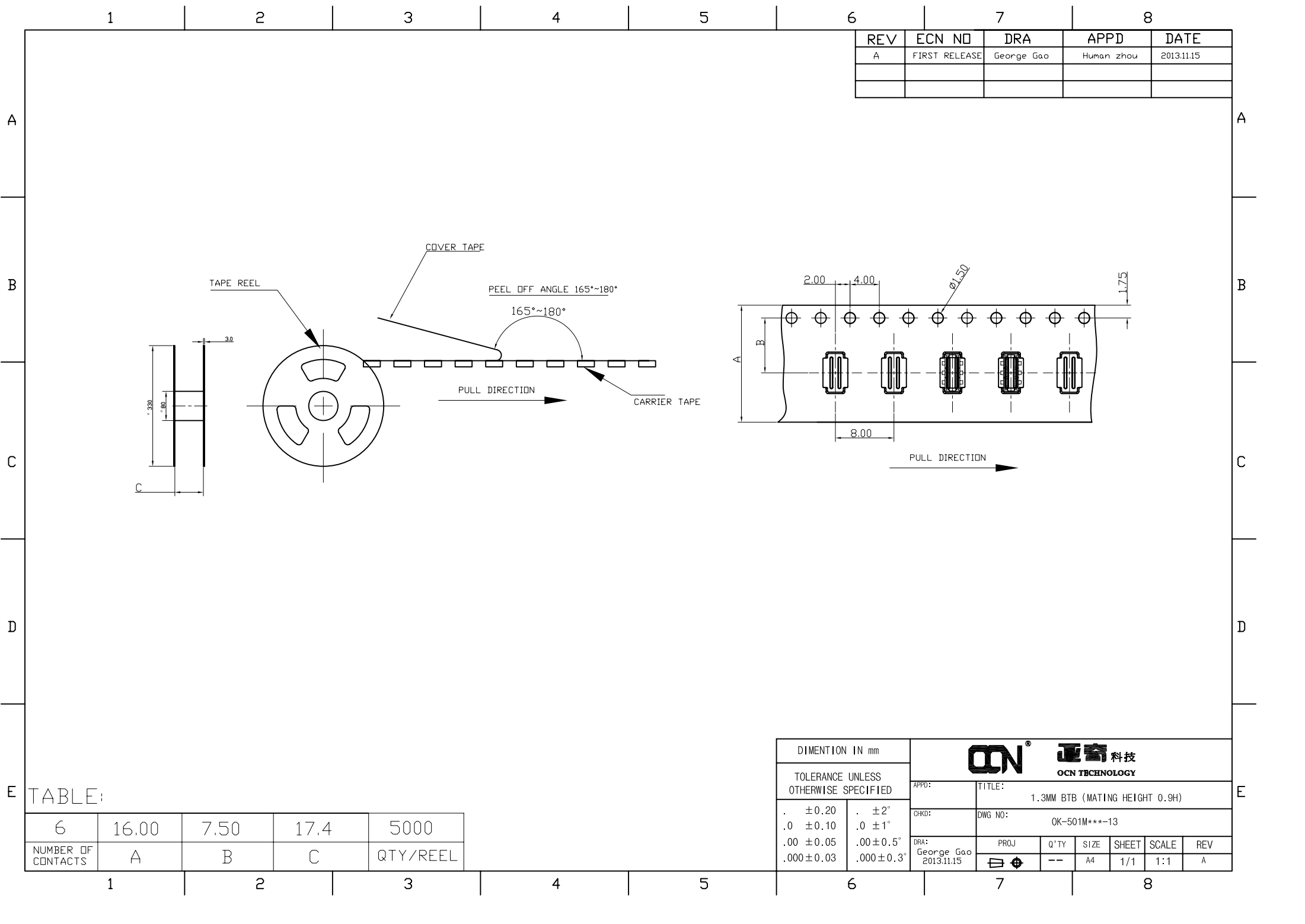
NUMBER OF CONTACTS

TABLE:

6	5.08	2.60
NUMBER OF CONTACTS	A	B

RECOMMENDED PCB LAYOUT

DIMENTION IN mm		OCN® 正奇科技 OCN TECHNOLOGY							
TOLERANCE UNLESS OTHERWISE SPECIFIED		APPD:	TITLE: 1.3MM BTB (MATING HEIGHT 0.9H)						
. ±0.20 .0 ±0.10 .00 ±0.05 .000±0.03		CHKD:	DWG NO: OK-501M***-13						
. ±2° .0 ±1° .00±0.5° .000±0.3°		DRA: George Gao 2013.11.15	PROJ	Q'TY	SIZE	SHEET	SCALE	REV	
				--	A4	1/1	1:1	A	



REV	ECN NO	DRA	APPD	DATE
A	FIRST RELEASE	George Gao	Human zhou	2013.11.15

TABLE:

6	16.00	7.50	17.4	5000
NUMBER OF CONTACTS	A	B	C	QTY/REEL

DIMENTION IN mm		<b>OCN</b> <sup>®</sup> 正奇科技 OCN TECHNOLOGY					
TOLERANCE UNLESS OTHERWISE SPECIFIED		APPD:	TITLE: 1.3MM BTB (MATING HEIGHT 0.9H)				
		CHKD:	DWG NO: OK-501M***-13				
		DRA: George Gao 2013.11.15	PROJ	Q'TY	SIZE	SHEET	SCALE
			⊕	--	A4	1/1	1:1
							REV A

A

B

C

D

E

1

2

3

4

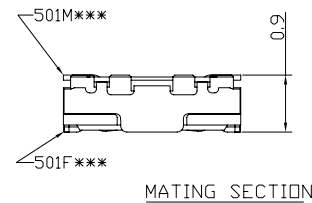
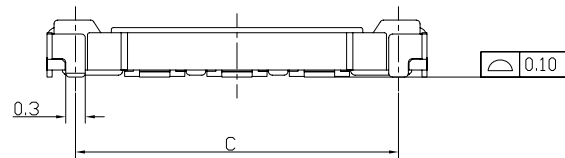
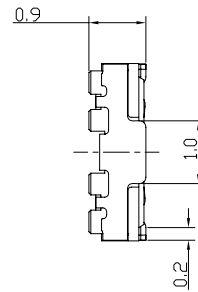
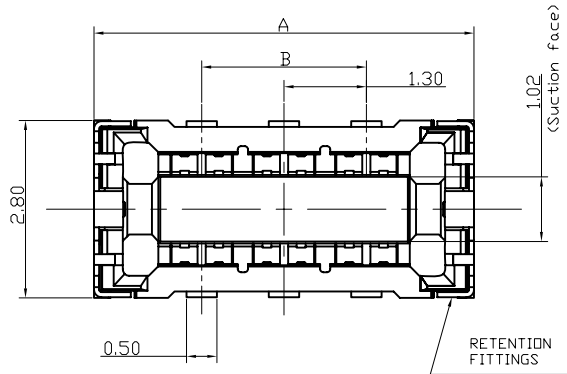
5

6

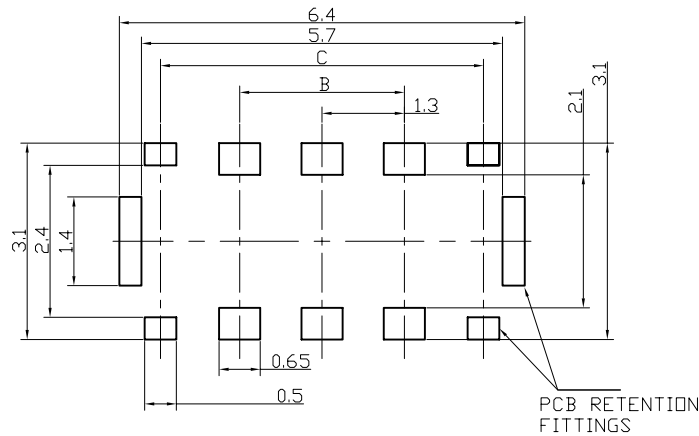
7

8

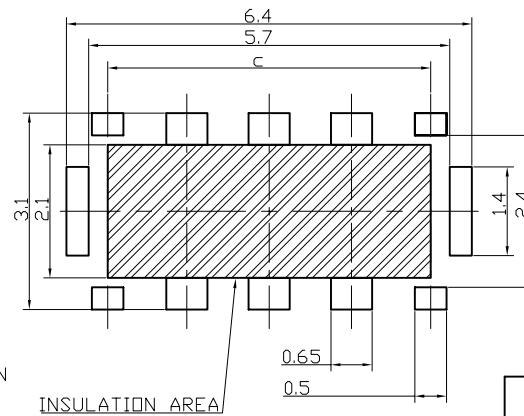
REV	ECN NO	DRA	APPD	DATE
A	FIRST RELEASE	George Gao	Human Zhou	2013.11.15



MATING SECTION



RECOMMENDED PCB LAYOUT



INSULATION AREA

## Specifications:

## 1) Material:

1-1.Molded portion: LCP resin ( UL94 V-0)

1-2.Contact and Post: Copper alloy.

## 2) Surface treatment:

2-1.Terminal portion: Base: Ni plating Surface: Au plating (except the terminal tips) ; Exposed nickel portions.

2-2.Metal clips: Base: Ni plating Surface: Au flash plating (except the terminal tips) Or Base: Ni plating Surface: Sn flash plating (except the terminal tips)

## 3) Characteristics:

3-1. Rated voltage: 30V AC/DC

3-2. Rated current: 4.0A/contact

3-3. Insulation resistance: Min. 1000M $\Omega$  (initial)

3-4. Breakdown voltage: 500V AC for 1 min.

3-5.Saltwater spray resistance (header and socket mated): 24 hours, insulation resistance min.100M $\Omega$ , contact resistance max. 20m $\Omega$ 3-6. Contact resistance: Power pin:20m $\Omega$ 、Signal pin :50m $\Omega$ 3-7. Ambient temperature: -25 $^{\circ}$ C~+85 $^{\circ}$ C3-8. Storage temperature: -25 $^{\circ}$ C~+85 $^{\circ}$ C (product only); -40 $^{\circ}$ C~+50 $^{\circ}$ C (emboss packing)

3-9. Composite insertion force: Max. 0.981N/contacts X contacts (initial)

3-10. Composite removal force: Min. 0.165N/contacts X contacts

3-11. Post holding force: Min. 0.49N/contacts

3-12. Insertion and removal life: 30 times

OK-501F\*\*\*-13

SOCKET

PITCH-1.3MM

NUMBER OF CONTACTS

TABLE:

6	6.00	2.60	5.1
NUMBER OF CONTACTS	A	B	C

1

2

3



4

5

6

7

8

DIMENTION IN mm		 正奇科技 OCN TECHNOLOGY							
TOLERANCE UNLESS OTHERWISE SPECIFIED		APPD:	TITLE: 1.3MM BTB (MATING HEIGHT 0.9H)						
. $\pm 0.20$ .0 $\pm 0.10$ .00 $\pm 0.05$ .000 $\pm 0.03$		CHKD:	DWG NO: OK-501F***-13						
. $\pm 2^{\circ}$ .0 $\pm 1^{\circ}$ .00 $\pm 0.5^{\circ}$ .000 $\pm 0.3^{\circ}$		DRA: George Gao 2013.11.15	PROJ	Q'TY	SIZE	SHEET	SCALE	REV	
				--	A4	1/1	1:1	A	

A

B

C

D

E

